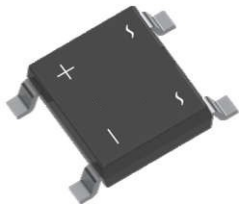
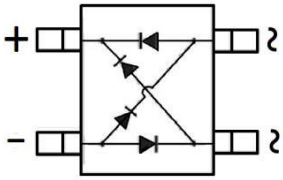
1A Surface Mount Glass Passivated Bridge Rectifier

Features

- Glass Passivated Chip Junction
- Reverse Voltage : 100 to 1000V
- Forward Current : 1A
- High Surge Current Capability
- High temperature soldering : 260°C/10s at terminals



ABS / LBF



Applications

- Switching power supply

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter		Symbol	ABS1	ABS2	ABS4	ABS6	ABS8	ABS10	Unit
Maximum Repetitive Peak Reverse Voltage		V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS Voltage		V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage		V_{DC}	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current@T_C=125℃		$I_{F(AV)}$	1.0						A
Peak Forward Surge Current 8.3mS single half sine wave superimposed on rated load(JEDEC method)		I_{FSM}	40						A
Maximum Instantaneous Forward Voltage @1.0A		V_F	1.0						V
Maximum DC Reverse Current at Rated DC Blocking Voltage	T_A=25℃	I_R	5.0						μA
	T_A=125℃		100						
Typical Junction Capacitance(Note 1)		C_J	18						pF
Typical Thermal Resistance(Note 2)		$R_{\theta JA}$	70						°C/ W
		$R_{\theta JC}$	18						
Operating Junction and Storage Temperature Range		T_J, T_{STG}	(-55 to+150)						°C

Notes:
1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with 4×1.5" ×1.5"（ 3.81 ×3.81 cm ）copper pad.

Ratings and Characteristic Curves (T_A=25℃ unless otherwise noted)

FIG.1 - Typical forward current derating curve

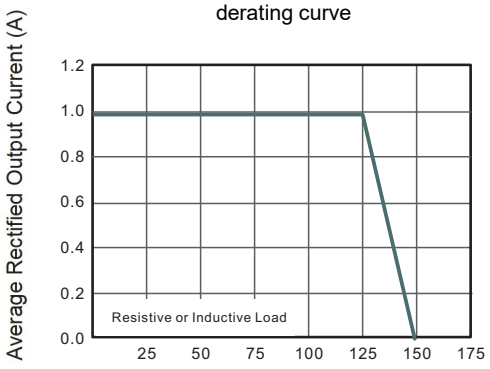


FIG.2 - Typical reverse Characteristics

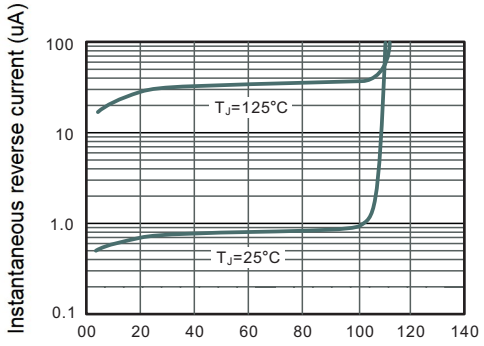


FIG.3 - Typical Instaneous Forward Characteristics

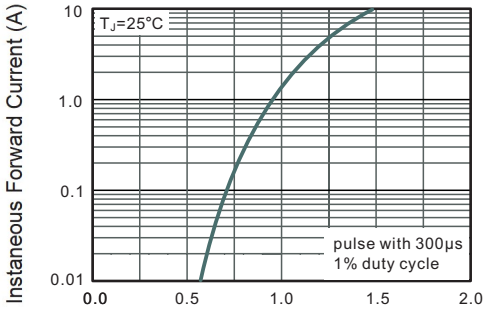


FIG.4 - Typical Junction Capacitance

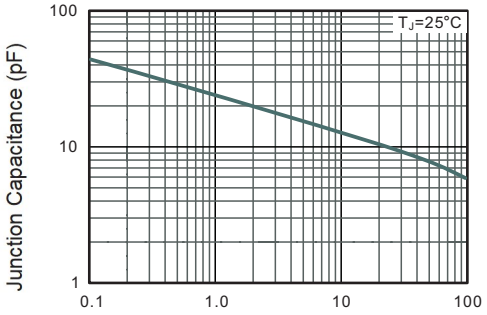
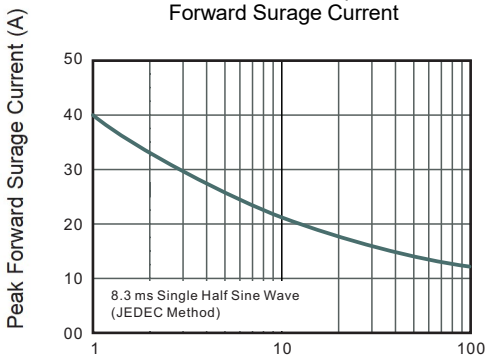
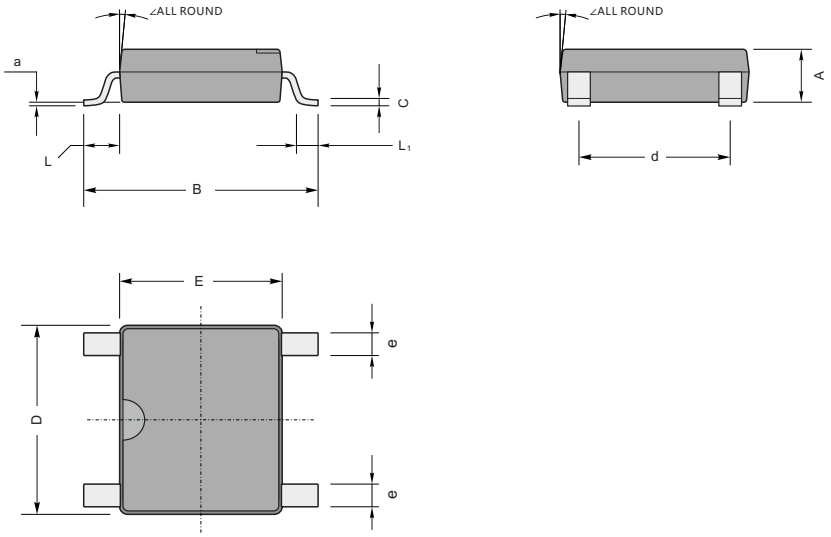


FIG.5 - Maximum Non-Repetitive Peak Forward Surage Current



Package Outlines (Dimensions in mm)

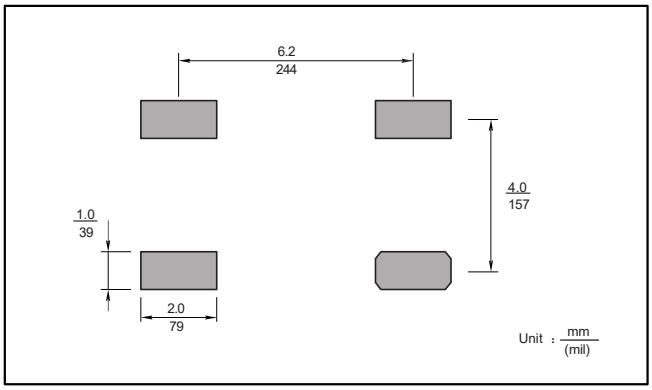
Plastic surface mounted package(ABS / LBF)



ABS/LBF mechanical data

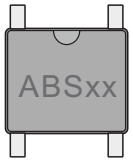
UNIT		A	C	D	E	B	d	e	L	L_1	a	∠
mm	max	1.5	0.22	5.3	4.6	6.5	4.2	0.7	0.95	0.6	0.2	5°
	min	1.3	0.15	5.0	4.3	6.1	3.8	0.5				
mil	max	59	8.7	209	181	256	165	28	37	24	8	
	min	51	5.9	197	169	240	150	20				

The recommended mounting pad size



Marking

Type number	Marking code
ABS1	ABS1
ABS2	ABS2
ABS4	ABS4
ABS6	ABS6
ABS8	ABS8
ABS10	ABS10



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